

L Number	Hits	Search Text	DB	Time stamp
17	196	(argon with physical) and nitrogen and sputtering	USPAT; US-PGPUB	2004/04/29 14:26
18	26	((argon with physical) and nitrogen and sputtering) and (RF with sputter\$3)	USPAT; US-PGPUB	2004/04/29 14:27
19	17	((argon with physical) and nitrogen and sputtering) and (RF with sputter\$3)) and @ad<20010828	USPAT; US-PGPUB	2004/04/29 14:34
22	3602	argon and nitrogen and (sputtering same (etching or cleaning))	USPAT; US-PGPUB	2004/04/29 15:15
20	21	argon and nitrogen and (sputtering same (etching or cleaning))	EPO; DERWENT	2004/04/29 14:30
23	2767	(argon and nitrogen and (sputtering same (etching or cleaning))) and @ad<20010828	USPAT; US-PGPUB	2004/04/29 15:17
24	2161	((argon and nitrogen and (sputtering same (etching or cleaning))) and @ad<20010828) and (hole or opening or trench or recess or aperture or via)	USPAT; US-PGPUB	2004/04/29 15:16
25	42	(physical with argon) and (((argon and nitrogen and (sputtering same (etching or cleaning))) and @ad<20010828) and (hole or opening or trench or recess or aperture or via))	USPAT; US-PGPUB	2004/04/29 14:37
26	1391	argon and nitrogen and (RF with sputtering) and (etching or cleaning)	USPAT; US-PGPUB	2004/04/29 15:20
27	833	(argon same nitrogen) and (RF with sputtering) and (etching or cleaning)	USPAT; US-PGPUB	2004/04/29 15:17
28	628	((argon same nitrogen) and (RF with sputtering) and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)	USPAT; US-PGPUB	2004/04/29 15:26
29	470	((argon same nitrogen) and (RF with sputtering) and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)) and @ad<20010828	USPAT; US-PGPUB	2004/04/29 15:26
30	2	(argon with physical) and (((argon same nitrogen) and (RF with sputtering) and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)) and @ad<20010828)	USPAT; US-PGPUB	2004/04/29 15:17
31	1	argon and nitrogen and (RF with sputtering) and (etching or cleaning)	EPO; JPO; DERWENT	2004/04/29 15:21
32	8	argon and nitrogen and bombardment and (etching or cleaning)	EPO; JPO; DERWENT	2004/04/29 15:24
33	2	helium and nitrogen and bombardment and (etching or cleaning)	EPO; JPO; DERWENT	2004/04/29 15:25
34	1009	helium and nitrogen and bombardment and (etching or cleaning)	USPAT; US-PGPUB	2004/04/29 15:25
35	851	(helium and nitrogen and bombardment and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)	USPAT; US-PGPUB	2004/04/29 15:26
36	653	((helium and nitrogen and bombardment and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)) and @ad<20010828	USPAT; US-PGPUB	2004/04/29 15:26
37	291	((helium and nitrogen and bombardment and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)) and @ad<20010828) and organic	USPAT; US-PGPUB	2004/04/29 15:27
38	0	((helium and nitrogen and bombardment and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)) and @ad<20010828) and organic) and (chemcial with nitrogen)	USPAT; US-PGPUB	2004/04/29 15:27
39	5	((helium and nitrogen and bombardment and (etching or cleaning)) and (hole or opening or trench or recess or aperture or via)) and @ad<20010828) and organic) and (physical with helium)	USPAT; US-PGPUB	2004/04/29 15:27